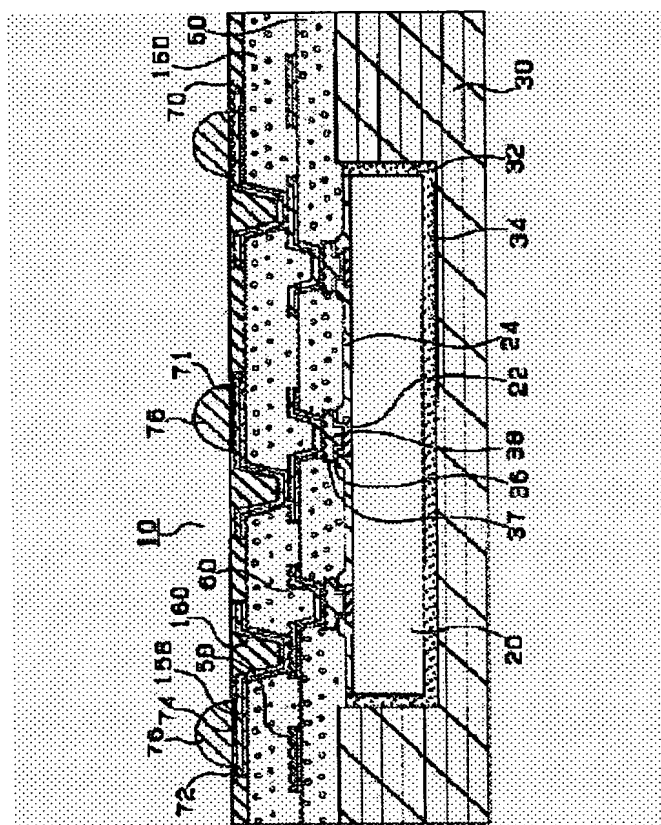


**METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE**

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**Abstract of JP2002170827**

**PROBLEM TO BE SOLVED:** To a semiconductor device which can be directly, electrically connected with a printed wiring board without interposing a lead component.  
**SOLUTION:** A transition layer 38 is placed on a die pad of IC chip 20 to be incorporated in a multi-layer printed wiring board 10. Thereby, an electrical connection between the IC chip 20 and the multi-layer printed wiring board 10 may be obtained without using any lead component and sealing resin. Additionally, a residual resin on a pad 24 can be avoided by locating the copper transition layer 38 on the die pad 24, and a connectivity between the die pad 24 and a via hole 60 and its reliability may be improved.



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